

MOUNTING APPARATUS AND METHOD OF CORRECTING OFFSET AMOUNT OF
THE SAME

ABSTRACT

Provided is a method including: a first chip-position calculation step of taking an image of an upper surface of a reference chip 12 and an image of a lower surface of a correction chip 13 using an upper/lower dual-view camera 20 to calculate positions of the chips 12 and 13; a second chip-movement step of moving the reference chip to a position, based on a displacement amount between the chips that has been calculated based on the positions of the chips, at which a distance between the chips corresponds to a predetermined offset amount, and then placing the correction chip 13 on the suction stage 11; a second chip-position calculation step of taking an image of an upper surface of the correction chip 13, and calculating a second position of the correction chip 13; and a correction amount calculation step of calculating a correction amount of the predetermined offset amount based on the position of the reference chip and the second position of the correction chip. This suppresses positional displacement of a mounting position over time, and thus improves mounting quality.

Fig. 4a - 4g